



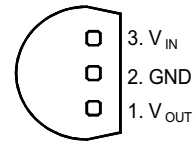
AMC7628

300mA LOW DROPOUT REGULATOR

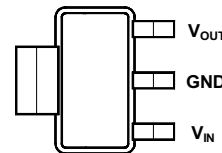
DESCRIPTION	FEATURES
<p>The AMC7628 series is a low dropout regulator rated for 300mA output current. AMC7628-5.0 can regulate with as low as 100mV headroom between the input and output voltages at 150mA output current, thus minimizing power dissipation. In addition, it can be used in applications where worst case supplies require a low Input-Output differential to maintain regulation. The AMC7628-3.3/5.0 is a fixed 3.3V/5.0V output voltage version and these features make it ideal for battery powered applications that require low dropout from supply. A reverse battery protection scheme limits the reverse current when the input voltage falls below the output</p>	<ul style="list-style-type: none"> ■ 1% internally trimmed output ■ Output current is excess of 300mA ■ Input-Output differential of typ. 0.3V at 300mA & low quiescent current □ Reverse battery protection □ Short circuit protection □ Internal thermal overload protection □ Available in 3L plastic TO-92 and surface mount SOT223 packages

APPLICATIONS	PACKAGE PIN OUT
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- Computer Monitors
- Battery Powered Circuitry
- Computer Add-On Cards
- USB Power
- DVD Driver
- Digital Camera



3-Pin Plastic TO-92
(Top View)

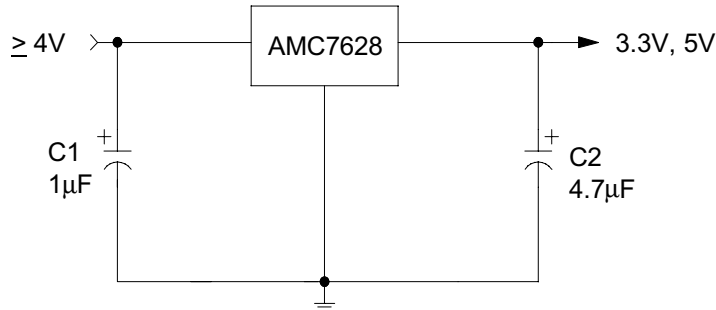


3-Pin Plastic SOT-223
Surface Mount
(Top View)

AMC7628-3.3 – 3.3V Fixed
AMC7628-5.0 – 5.0V Fixed

ORDER INFORMATION			
T_A (°C)	LP	Plastic TO-92 3-pin	SK
		Plastic SOT-223 3-pin	
0 to 70	AMC7628-X.XLP		AMC7628-X.XSK
<p>Note: All surface-mount and TO-92 packages are available in Tape & Reel. Append the letter "T" to part number (i.e. AMC7628-X.XLPT or AMC7628-X.XSKT).</p>			

TYPICAL APPLICATION



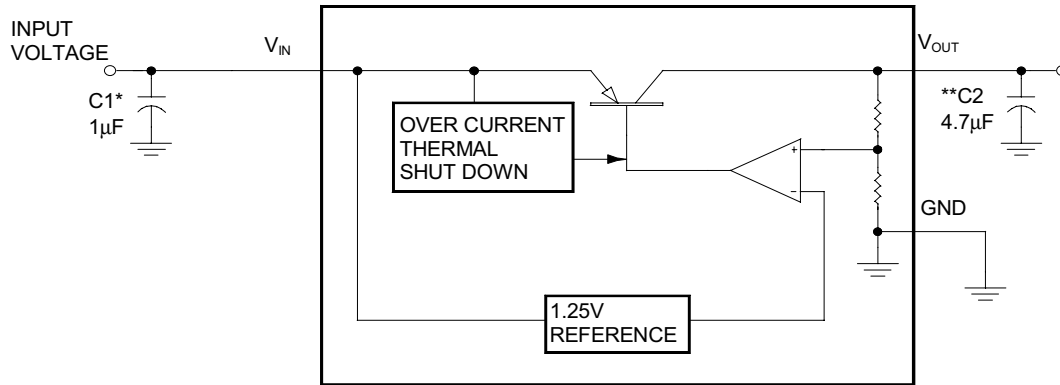
ABSOLUTE MAXIMUM RATINGS (Note 1)

Input Voltage (V _{IN})	13V
Operating Junction temperature	
Plastic (LP, SK Package)	150 °C
Storage Temperature Range	-65 °C to 150 °C
Lead temperature (Soldering, 10 seconds)	300 °C
Note 1: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal.	

THERMAL DATA

LP PACKAGE:	
Thermal Resistance-Junction to Ambient, θ _{JA}	156 °C/W
SK PACKAGE:	
Thermal Resistance-Junction to Tab, θ _{JT}	15 °C/W
Thermal Resistance-Junction to Ambient, θ _{JA}	136 °C/W
Junction Temperature Calculation: T _J = T _A + (P _D × θ _{JA}).	
The θ _{JA} numbers are guidelines for the thermal performance of the device/pc-board system.	
All of the above assume no ambient airflow.	

BLOCK DIAGRAM



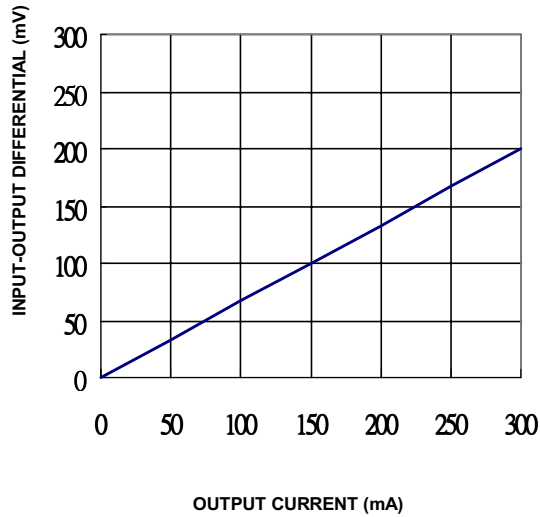
- * REQUIRED IF REGULATOR IS LOCATED FAR FROM POWER SUPPLY FILTER
- ** DESIGN C2 AS CLOSE TO V_{OUT} PIN AS POSSIBLE

RECOMMENDED OPERATING CONDITIONS					
Parameter	Symbol	Recommended Operating Conditions			Units
		Min.	Typ.	Max.	
Input Voltage	V_{IN}	4.0		12	V
Load Current (with adequate heatsinking)	I_O	5		300	mA
Input Capacitor (V_{IN} to GND)		0.1			μ F
Output Capacitor with ESR of 10Ω max., (V_{OUT} to GND)		4.7			μ F
Junction temperature	T_j			125	$^{\circ}$ C

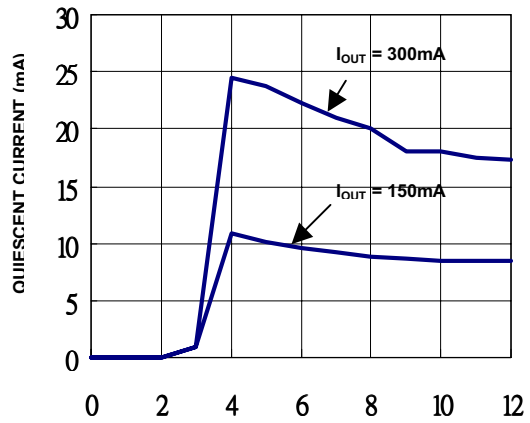
ELECTRICAL CHARACTERISTICS							
Unless otherwise specified, these specifications apply over the operating ambient temperature of 0° C to $+70^{\circ}$ C for AMC7628; $V_{IN} = 7V$, $I_O = 100mA$, $C_{OUT} = 4.7\mu F$, and are for DC characteristics only. (Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)							
Parameter	Symbol	Test Conditions	AMC7628			Units	
			Min.	Typ.	Max.		
Output Voltage	AMC7628-3.3 AMC7628-5.0	V_O	$I_O = 10mA$, $T_A = 25^{\circ}C$	3.267 4.950	3.3 5.0	3.333 5.050	V
Line Regulation		ΔV_{OI}	$V_O + 2V \leq V_{IN} \leq 12V$, $I_O = 5mA$		10	50	mV
Load regulation		ΔV_{OL}	$50mA \leq I_O \leq 300mA$		10	50	mV
Dropout Voltage		ΔV	$I_O = 100mA$		100	300	mV
			$I_O = 300mA$		200	400	
Quiescent Current		I_Q	$I_O \leq 5mA$, $4V \leq V_{IN} \leq 12V$		3	10	mA
			$I_O = 100mA$		6	15	
			$I_O = 300mA$		20	32	
Current Limit		I_{CL}	$V_{IN} = 10V$	300	330		mA
Output Noise Voltage (Note 1)		$V_{O_{RMS}}$	10HZ – 100kHz, $I_O = 5mA$		150		μV_{RMS}
Long Term Stability (Note 1)					20		mV/1000hr
Ripple rejection (Note 1)		R_R	$f_O = 120HZ$, $1V_{RMS}$, $I_O = 100mA$		66		dB
Note 1: These parameters, although guaranteed, are not tested in production.							

CHARACTERISTICS CURVES

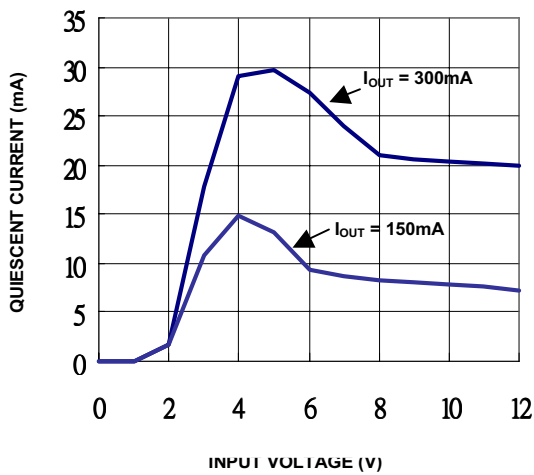
Dropout Voltage (AMC7628-5.0V)



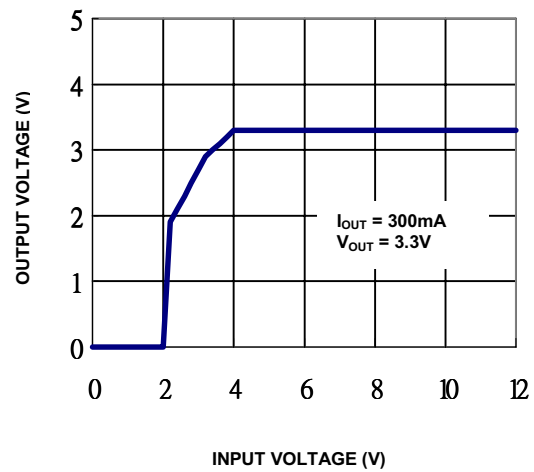
Quiescent Current (AMC7628-3.3)



Quiescent Current (AMC7628-5.0)

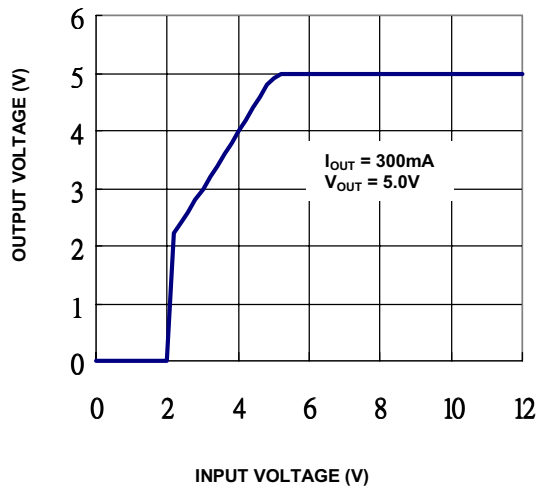


Input Voltage vs. Output Voltage

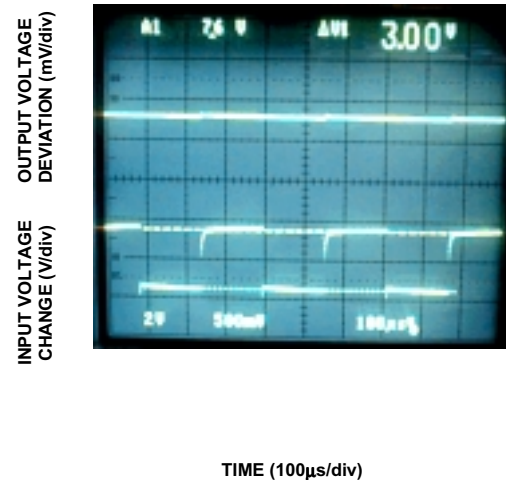


CHARACTERISTICS CURVES

**Input Voltage vs.
Output voltage**



Line Transient Response



Application Note:

Maximum Power Calculation:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_{A(MAX)}}{\theta_{JA}}$$

$T_J(^{\circ}C)$: Maximum recommended junction temperature

$T_A(^{\circ}C)$: Ambient temperature of the application

$\theta_{JA}(^{\circ}C/W)$: Junction-to-junction temperature thermal resistance of the package, and other heat dissipating materials.

The maximum power dissipation of a single-output regulator :

$$P_{D(MAX)} = [(V_{IN(MAX)} - V_{OUT(NOM)}) \times I_{OUT(NOM)} + V_{IN(MAX)} \times I_Q]$$

Where: $V_{OUT(NOM)}$ = the nominal output voltage

$I_{OUT(NOM)}$ = the nominal output current, and

I_Q = the quiescent current the regulator consumes at $I_{OUT(MAX)}$

$V_{IN(MAX)}$ = the maximum input voltage

Then $\theta_{JA} = (150^{\circ}C - T_A)/P_D$

Thermal consideration:

When power consumption is over about 404 mW (SOT223 package, at $T_A=70^{\circ}C$), additional heat sink is required to control the junction temperature below $125^{\circ}C$.

The junction temperature is: $T_j = P_D (\theta_{JT} + \theta_{CS} + \theta_{SA}) + T_A$

$P_D \equiv$ Dissipated power.

$\theta_{JT} \equiv$ Thermal resistance from the junction to the mounting tab of the package.

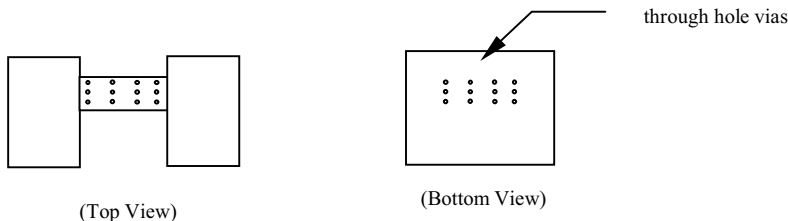
$\theta_{CS} \equiv$ Thermal resistance through the interface between the IC and the surface on which it is mounted.
(typically, $\theta_{CS} < 1.0^{\circ}C/W$)

$\theta_{SA} \equiv$ Thermal resistance from the mounting surface to ambient (thermal resistance of the heat sink).

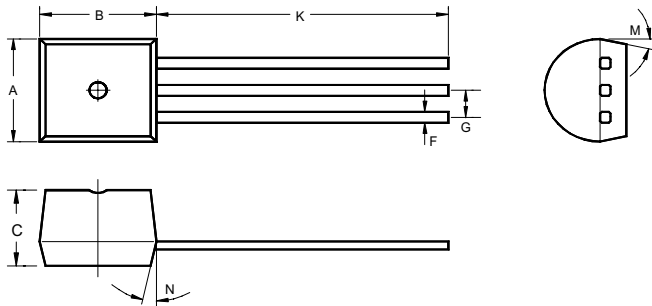
If PC Board copper is going to be used as a heat sink, below table can be used to determine the appropriate size of copper foil required. For multi-layered PCB, these layers can also be used as a heat sink. They can be connected with several through hole vias.

PCB $\theta_{SA} (^{\circ}C/W)$	59	45	38	33	27	24	21
PCB heat sink size (mm ²)	500	1000	1500	2000	3000	4000	5000

Recommended figure of PCB area used as a heat sink.



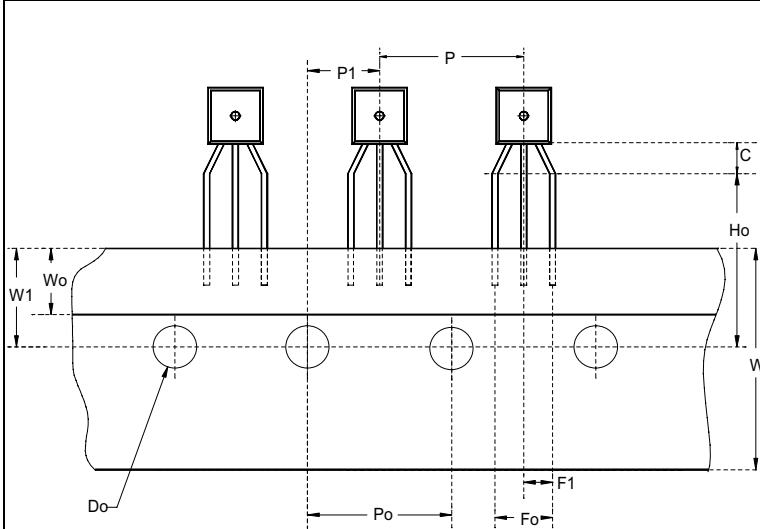
3-Pin Plastic TO-92 (LP)



Note: For TO-92 in tape and reel, refer to TO-92 package and carrier dimension data for lead dimensions.

	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.175	0.180	0.205	4.45	4.57	5.21
B	0.170	0.180	0.210	4.32	4.57	5.33
C	0.125	0.142	0.165	3.18	3.62	4.19
F	-	0.015	-	-	0.38	-
G	-	0.050	-	-	1.27	-
J	-	0.150	-	-	3.81	-
K	0.500	0.580	-	12.70	14.73	-
M	-	5°	-	-	5°	-
N	-	5°	-	-	5°	-

3-Pin Plastic TO-92 Package(Taped and Reeled) Carrier Dimensions



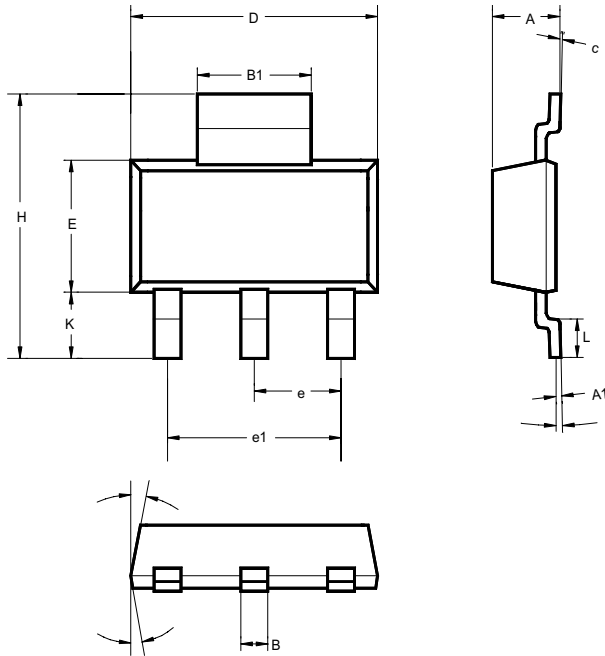
Note: For 3L TO92, 2,000 units per Reel

	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
C	0.079	-	-	2.00	-	-
P	0.480	0.500	0.520	12.2	12.7	13.2
Po	0.488	0.500	0.512	12.4	12.7	13.0
Do	0.150	0.157	0.165	3.8	4.0	4.2
P1	0.230	0.250	0.256	5.85	6.35	6.85
Fo	0.165	0.197	0.220	4.2	5.0	5.6
W	0.669	0.709	0.748	17.0	18.0	19.0
Ho	0.610	0.630	0.649	15.5	16.0	16.5
W0	0.224	0.236	0.248	5.7	6.0	6.3
W1	0.335	0.354	0.374	8.5	9.0	9.5

3-Pin Surface Mount SOT-223 (SK)

AMC7628

300mA LOW DROPOUT REGULATOR



	MILLIMETERS		
	MIN	TYP	MAX
A	1.50	1.65	1.80
A1	0.02	0.05	0.08
B	0.60	0.70	0.80
B1	2.90	-	3.15
c	0.28	0.30	0.32
D	6.30	6.50	6.70
E	3.30	3.50	3.70
e	2.3 BSC		
e1	4.6 BSC		
H	6.70	7.00	7.30
L	0.91	1.00	1.10
K	1.50	1.75	2.00
α	0°	5°	10°
β		3°	

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U.S.

ADD Microtech Inc.
492 Altamont Drive
Milpitas, CA 95035

TEL: (408) 9410420
FAX: (408) 9410864

Asia Pacific region

ADD Microtech Corp
3F, 132, Sec. 4, Chung Hsiao E. Rd.,
Taipei, Taiwan

TEL: 2-27760166
FAX: 2-27764208